RMA 202-35

Solder plus Support

Rosin Mildly Activated Liquid Flux

Features:

- Rosin Activated
- Non-Corrosive Residues
- Residues Removable with a Saponifier
- Can be Foamed, Sprayed, Dipped or Brushed
- Improved Soldering Performance

Description:

RMA 202-35 is a medium solids, mildly activated liquid flux with a solvent rosin activation formulated to provide a post-process flux residue that is both insulating and non-hydroscopic and does not require cleaning. As a mildly activated rosin based flux, RMA 202-35 offers a wide process window, good cleaning properties, and excellent thermal transfer.

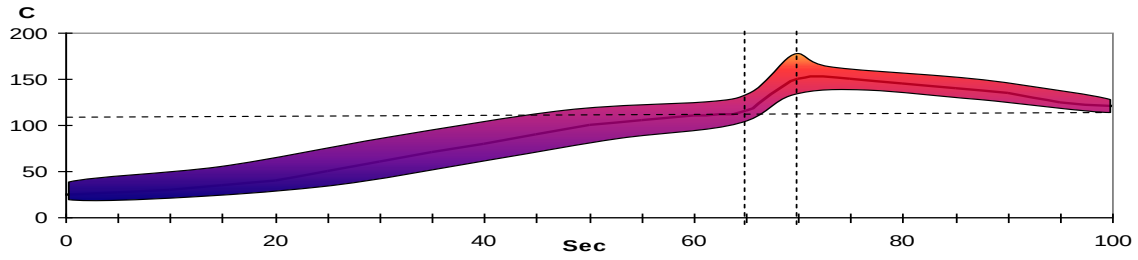
Flux Application:

- For most tinning operations, the component lead should be immersed into the flux to a depth of approximately 50% of the desired solder flow in order to prevent excessive flux application.
- For spray fluxing applications, RMA 202-35 is ready to use directly from its container, no thinning is required.
- When spray fluxing, it is imperative that proper flux coverage and uniformity be achieved and maintained. A dry flux coating of 500 to 1500 micrograms per square inch is recommended as a starting point.
- When foam fluxing, air stones should be supplied with compressed air, free of oil and moisture. Adjust foam head to achieve a uniform distribution of small bubbles for optimum flux coverage.
- During foaming applications it is periodically necessary to add flux thinner to replace that which is lost through evaporation. AIM Common Flux Thinner is recommended.

Process Control:

Specific gravity should be monitored and controlled either with an automated flux density controller, or manually with a hydrometer. Specific gravity should be maintained at .84 ± .01 for optimum performance. Dump and refill flux pot with fresh flux at least once per week when used daily. For spray flux applications, ensure proper coverage of pwb is maintained.

Typical Thermal Profile:



RATE of RISE 2-3ºC / SEC MAX	PROGRESS THROUGH 66°C - 77°C (150 - 170ºF)	PCB TOP SIDE TEMP 87°C - 115°C (190ºF - 240ºF)	COOLDOWN ≤ 4ºC
	≤ 40 SECONDS	JUST BEFORE WAVE	

Cleaning:

Post process residues are considered to be non-corrosive, and may remain on the work piece post-soldering. If residue removal is required for conformal coating or conformance to specific ionic cleanliness specifications, this can be easily accomplished with the use of a saponifier and water. AIMTERGE 520A is recommended.

Handling and Storage:

- RMA 202-35 has an unopened shelf life of 1 year when stored at room temperature.
- Do not store near fire or flame.
- Keep away from sunlight as it may degrade product.
- RMA 202-35 is shipped ready-to-use, no mixing necessary.
- Do not mix used and unused chemical in the same container.
- Reseal any opened containers.

Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

Physical Properties:

Parameter	Value
J-STD-004	ROL0
Visual	Amber
Odor	Aromatic (Slightly)
Solids Content	35 %

Parameter	Value
Specific Gravity	0.86 ± .01 (water = 1)
Flash Point	< 10°C
Acid Number	58.02 ± 0.80

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